

OP2177 Die Revision and Wafer Fabrication Process Change

**Qualification Results Summary of OP2177 Die Revision
and Wafer Fabrication Process Change**

QUALIFICATION RESULTS			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	1 x 30	Pass
Early Life Failure (ELF)	JEDEC <i>MIL-STD-883-M1015</i>	3 x 800	Pass
High Temperature Operating Life (HTOL)	JEDEC <i>JESD22-A108</i>	3 x 82	Pass
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 82	Pass
Latch-Up	JEDEC <i>JESD78</i>	3/test	Pass ± 200 mA, ± 22.5 V
Electrostatic Discharge <i>Human Body Model</i>	ESDA/JEDEC <i>JDS-001-2011</i>	3/voltage	Pass ± 1000 V
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	Pass ± 1250 V

*Preconditioned per JEDEC/IPC J-STD-020